

Title (en)

METHOD FOR PRODUCING A MULTI-LAYER SUBSTRATE AND MULTI-LAYER SUBSTRATE

Title (de)

VERFAHREN ZUR HERSTELLUNG EINES MEHRSCICHTSUBSTRATS UND MEHRSCICHTSUBSTRAT

Title (fr)

PROCÉDÉ POUR PRODUIRE UN SUBSTRAT MULTICOUCHE ET SUBSTRAT MULTICOUCHE

Publication

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Application

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Abstract (en)

[origin: WO2016030195A1] The invention relates to a method for producing a multi-layer substrate (1), wherein a main body (26), having a plurality of ceramic layers (2), is provided, wherein at least one layer (2) has a hole (27). To form an inter-layer connection (4, 18, 20, 21), the hole (27) is filled with a metal by precipitating the metal from a solution. The invention further relates to a multi-layer substrate, wherein an inter-layer connection (4, 18, 20, 21) in the interior of the main body (26) is connected to a further connection (11), wherein the inter-layer connection (4, 18, 20, 21) has a different material than the further connection (11) and/or is produced by means of a different method.

IPC 8 full level

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